

## Abstract of the Disclosure

For a three-layer flexible board, there is provided a copper alloy foil that requires no roughening processing, that has good adhesion with an adhesive containing an epoxy resin, that can be laminated to form a copper-clad laminate, that has a low surface roughness, and that has high conductivity and strength. The copper alloy of the foil contains at least one of 0.01-2.0 weight percent Cr and 0.01-1.0 weight percent Zr or contains 1.0-4-8 weight percent Ni and 0.2-1.4 weight percent Si. Good adhesion of the copper alloy foil to a resin substrate with an adhesive containing an epoxy resin is obtained by setting the thickness of the anticorrosive coating to less than 3 nm; the surface roughness of the copper alloy foil is below 2  $\mu\text{m}$  expressed as ten-point average surface roughness ( $R_z$ ); and, without roughening processing, the 180° C peel strength, after adhesion of the copper alloy foil to the board film by means of an adhesive containing an epoxy resin, is greater than 8.0 N/cm.